



Material Content Data Sheet



Sales Product Name		ESD112-B1-02ELS E6327		Issued		29. August 2013		
MA#		MA001085708						
Package		PG-TSSLP-2-4		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3262	
	noble metal	gold	7440-57-5	0.003	1.27		12661	
	inorganic material	silicon	7440-21-3	0.020	9.38	10.98	93810	109733
leadframe	non noble metal	nickel	7440-02-0	0.108	50.59	50.59	505908	505908
wire	noble metal	gold	7440-57-5	0.003	1.47	1.47	14748	14748
encapsulation	organic material	carbon black	1333-86-4	0.000	0.16		1633	
	plastics	epoxy resin	-	0.010	4.74		47432	
	inorganic material	silicondioxide	60676-86-0	0.059	27.80	32.70	278047	327112
leadfinish	noble metal	gold	7440-57-5	0.004	1.73	1.73	17262	17262
plating	noble metal	palladium	7440-05-3	0.001	0.60		5986	
	noble metal	gold	7440-57-5	0.004	1.93	2.53	19251	25237
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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